# 2SD1538, 2SD1538A

### Silicon NPN epitaxial planar type

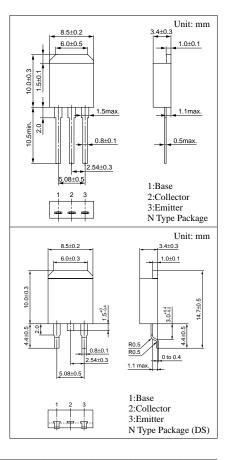
For low-voltage switching Complementary to 2SB1070 and 2SB1070A

#### Features

- ullet Low collector to emitter saturation voltage  $V_{\text{CE(sat)}}$
- High-speed switching
- N type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

### Absolute Maximum Ratings (T<sub>C</sub>=25°C)

Parameter		Symbol	Ratings	Unit	
Collector to	2SD1538	37	40	V	
base voltage	2SD1538A	$V_{CBO}$	50		
Collector to	2SD1538	37	20	V	
emitter voltage	2SD1538A	$V_{CEO}$	40		
Emitter to base voltage		$V_{\rm EBO}$	5	V	
Peak collector current		$I_{CP}$	8	A	
Collector current		$I_{C}$	4	A	
Collector power	T <sub>C</sub> =25°C	D	25	W	
dissipation	Ta=25°C	$P_{C}$	1.3		
Junction temperature		T <sub>j</sub>	150	°C	
Storage temperature		$T_{stg}$	-55 to +150	°C	



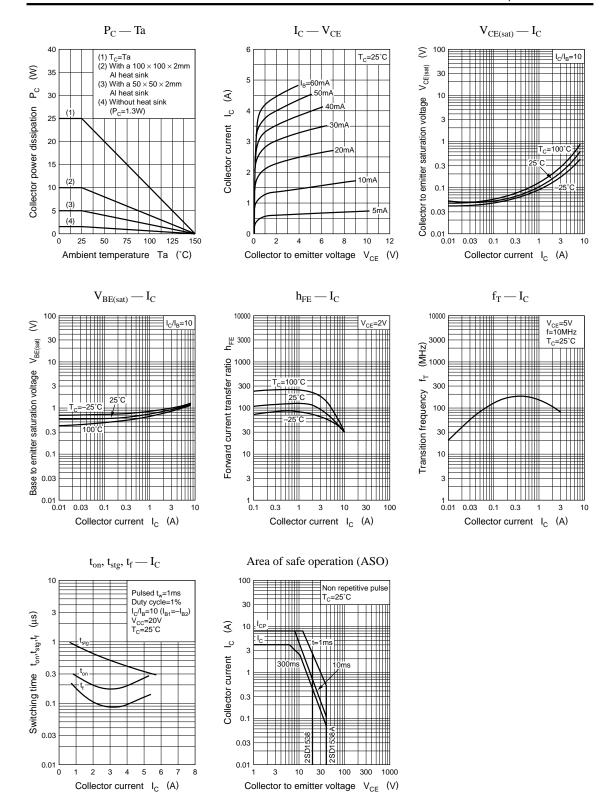
#### ■ Electrical Characteristics (T<sub>C</sub>=25°C)

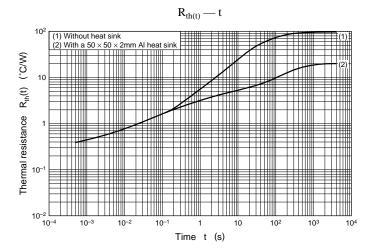
Parameter		Symbol	Conditions	min	typ	max	Unit
Collector cutoff	2SD1538	,	$V_{CB} = 40V, I_E = 0$			50	μА
current	2SD1538A	I <sub>CBO</sub>	$V_{CB} = 50V, I_{E} = 0$			50	
Emitter cutoff current		I <sub>EBO</sub>	$V_{EB} = 5V, I_C = 0$			50	μА
Collector to emitter	2SD1538	V <sub>CEO</sub>	$I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$	20			V
voltage	2SD1538A			40			
Forward current transfer ratio		h <sub>FE1</sub>	$V_{CE} = 2V, I_{C} = 0.1A$	45			
		h <sub>FE2</sub> *	$V_{CE} = 2V$ , $I_C = 1A$	90		260	
Collector to emitter saturation voltage		V <sub>CE(sat)</sub>	$I_C = 2A, I_B = 0.1A$			0.5	V
Base to emitter saturation voltage		V <sub>BE(sat)</sub>	$I_C = 2A, I_B = 0.1A$			1.5	V
Transition frequency		$f_{T}$	$V_{CE} = 5V, I_C = 0.5A, f = 10MHz$		120		MHz
Turn-on time		t <sub>on</sub>	$I_C = 2A, I_{B1} = 0.2A, I_{B2} = -0.2A,$ $V_{CC} = 20V$		0.2		μs
Storage time Fall time		t <sub>stg</sub>			0.5		μs
		t <sub>f</sub>			0.1		μs

#### \*hFE2 Rank classification

Rank	Q	P	
h <sub>FE2</sub>	90 to 180	130 to 260	

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